



## FLOW SOLDERING FLUX TYPE 40S2A

- **MBO 40S2A** is specifically designed to leave low or no residues after soldering, so eliminating the need for post cleaning of printed circuit boards, offering an appreciable reduction of production time and costs.
- Dirt accumulation in machines and on circuit boards carriers is significantly reduced.
- Soldering efficiency is equal to or better than resinous flux, type RMA.
- Halide free, it leaves no corrosive elements after processing.
- **MBO 40S2A** flux is manufactured to conform with French Standards NFC 90550, German DIN 8511 and British Standard BS 5625.

### Physiochemical Characteristics:

Solution	: Alcoholised
Colour	: Colourless
Density at 20°C	: 0.806 +/- 0.5%
Non volatile content	: 1.8 %
Chlorine rate	: Halide free
Flash point	: 12°C
Acidity	: 15.1 +/- 0.5 mg/g
Corrosiveness	: None
Insulation resistance	: > 100 GΩ
Efficiency (SAR)	: <30° SAR – Grade III

### Application Notes:

**Flux MBO 40S2A** can be used with many types of fluxing systems to include spray, foam and dipping in all types of automatic soldering machines using a single or double wave.

Carry out a regular check of the flux density or acidity index and maintain the level by adding DILUTANT D40S. Nominal density is 0.800 to 0.810 @ 20°C.

The circuit board topside drying temperature after fluxing should be 80 to 120°C.  
The alloy bath temperature between 240 and 260°C.

Conveyor speed should be between 0.8 and 2 meters per minute, depending upon the type of circuit being soldered. Contact time between circuit and solder wave should not exceed 3 seconds.

### Health and Safety:

As with all soldering fluxes, **MBO 40S2A** must be used in a well ventilated area away from any source of flame or ignition (COSH sheet available).

### Packaging:

Throwaway 10 litre plastic containers.

### Storage:

In original hermetically sealed containers, stored at an ideal temperature near 20°C for 12 months maximum.